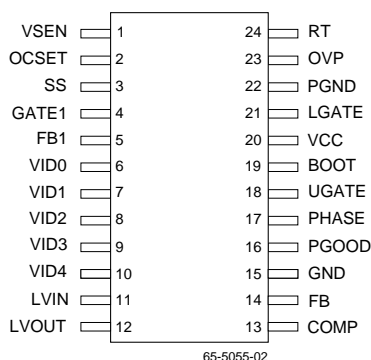


Pin Assignments



65-5055-02

Pin Definitions

Pin Number	Pin Name	Pin Function Description
1	VSEN	This pin is connected to the converter's output voltage. The PGOOD and OVP comparator circuits use this signal to report output voltage status and for overvoltage protection.
2	OCSET	Connect a resistor (ROCSET) from this pin to the drain of the upper MOSFET. An internal 200µA current source (I _{OCS}) and the upper MOSFET R _{DS(ON)} set the converter peak over-current trip point: $I_{PEAK} = \frac{I_{OCS} \cdot R_{OCSET}}{R_{DS(ON)}}$
3	SS	Soft Start. A capacitor from this point to ground together with an internal 10µA will cause the output duty cycle to increase slowly
4	GATE1	Linear Regulator Error Amplifier Output.
5	FB1	Linear Regulator Error Amplifier Inverting Input. When FB1 and GATE1 are tied together the Output Voltage = V _{ref}
6-10	VID0-4	DAC inputs. Used to adjust the output voltage to the voltage required by the processor.
11	LVIN	Input for fixed linear regulator
12	LVOUT	2.5V fixed output from fixed linear regulator
13	COMP	PWM Loop Error Amplifier output.
14	FB	PWM Loop Voltage Feedback. Inverting input of Error Amplifier.
15	GND	Analog Ground.
16	PGOOD	Power good. This pin is pulled low when any of the regulator's output is not within the spec.
17	PHASE	Connect the PHASE pin to the upper MOSFET source. This pin is used to monitor the voltage drop across the MOSFET for over-current protection. This pin also provides the return path for the upper gate drive.
18	UGATE	Upper MOSFET gate driver
19	BOOT	Upper MOSFET bootstrap.
20	VCC	12V bias supply.
21	LGATE	Low MOSFET gate driver.
22	PGND	Power ground.
23	OVP	Over-voltage Protection. This pin drives an external SCR.
24	RT	Oscillator switching frequency adjust according to the following equations: $f_s = 200\text{kHz} + \frac{3.5 \times 10^6 [\text{KHz} \times \text{Kohm}]}{R_T [\text{Kohm}]} \quad (R_T \text{ to GND})$ $f_s = 200\text{kHz} - \frac{3 \times 10^5 [\text{KHz} \times \text{Kohm}]}{R_T [\text{Kohm}]} \quad (R_T \text{ to 12V})$

Absolute Maximum Ratings

Parameter	Min.	Max.
Power Input Voltage, V_{in}		6V
Supply Voltage V_{cc}		13.5V
Boot Voltage, $V_{BOOT-VPHASE}$		13.5V
I/O Voltages	GND-0.3V	$V_{in}+0.3V$
ESD Classification		Class 2

Operating Conditions

Parameter	Min.	Max.
Supply Voltage	+12V -10%	+12+10%
Ambient Temperature	0°C	70°C
Junction Temperature	0°C	125°C

Thermal Information

Parameter	Conditions	Min.	Typ.	Max.
Thermal Resistance, Θ_{JA}	SOIC SSOP		80 89	°C/W
Maximum Junction Temperature				150°C
Storage Temperature		-65°C		150°C
Maximum Lead Temperature	Soldering 10 Seconds			300°C

Electrical Specifications

($V_{CC}=12V$, $F_{OSC}=200KHz$ and $T_A=25^\circ C$ using circuit in figure 1, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Units
PWM Section						
VCC Supply Current						
Nominal Supply	ICC	UGATE and LGATE Open	–	24	35	mA
Power-On Reset						
Rising VCC Threshold		VOCSET = 4.5V	–	–	10.4	V
Falling VCC Threshold		VOCSET = 4.5V	8.8	–	–	V
Rising VOCSET Threshold			–	1.26	–	V
Oscillator						
Free Running Frequency	FS	RT = OPEN	185	200	215	kHz
Ramp Amplitude	ΔV_{OSC}	RT = OPEN	–	1.9	–	V _{P-P}
Reference and DAC						
Input Voltage Setpoint		$I_{LOAD} = 0.8A$, $V_{OUT}=2.000V$ $V_{OUT}=1.550V$	1.980 1.534	2.000 1.550	2.020 1.566	V V
Error Amplifier						
DC Gain	ADC		–	88	–	dB
Gain-Bandwidth Product	GBW		–	15	–	MHz
Slew Rate	SR	COMP = 10pF	–	6	–	V/ μs

Electrical Specifications (continued)

(VCC=12V, FOSC=200KHz and TA=25°C using circuit in figure 1, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Gate Driver						
Upper Gate Source Current	IUGATE	VBOOT - VPHASE = 12V		1	–	A
Lower Gate Source Current	ILGATE	VCC = 12V, VLGATE = 6V		1	–	A
Protection						
Over-Voltage Trip (VSEN/DACOUT)			–	115	120	%
OCSET Current Source	IOCSET	VOCSET = 4.5VDC	170	200	230	μA
OVP Sourcing Current	IOVP	VSEN = 5.5V; VOVP = 0V	60	–	–	mA
Soft Start Current	ISS		–	10	–	μA
Power Good						
Upper Threshold (VSEN /DACOUT)		VSEN Rising	106	–	111	%
Lower Threshold (VSEN /DACOUT)		VSEN Falling	89	–	94	%
Hysteresis (VSEN /DACOUT)		Upper and Lower Threshold	–	2	–	%
PGOOD Voltage Low	VPGOOD	IPGOOD = -5mA	–	0.5	–	V
Adjustable Linear Regulator						
Output Voltage		Set by external resistors	1.3			V
Output Voltage Precision		ILOAD = 50 mA to 5.4A VCC = 12V ± 10% TA = 0 to 70°C	-2		+2	%
Under Voltage Level		Power good trigger point		60		%
Controller Output Current	GATE 1		20			mA
Output Transient Tolerance		50mA to 4.4 Amp Set by ESR of output caps	-135		135	mV
Bias Current	FB 1			1		μA
Feedback Voltage	FB 1			1.265		V
Fixed Linear Regulator						
Output Voltage	VOUT	ILOAD ≤ 100mA VCC = 12V ± 10% VIN = 5V	2.375	2.5	2.625	V
Under Voltage Level		Power good trigger point		60		%
Output Current	IOUT	VCC = 12V ± 10% VIN = 5V	100			mA
Over Current Trip Point		VCC = 12V ± 10% VIN = 5V		150		mA
ISC Foldback		VOUT = 0		25		mA
Input Voltage	VIN	VCC = 12V ± 10%	4.75	5	5.25	V

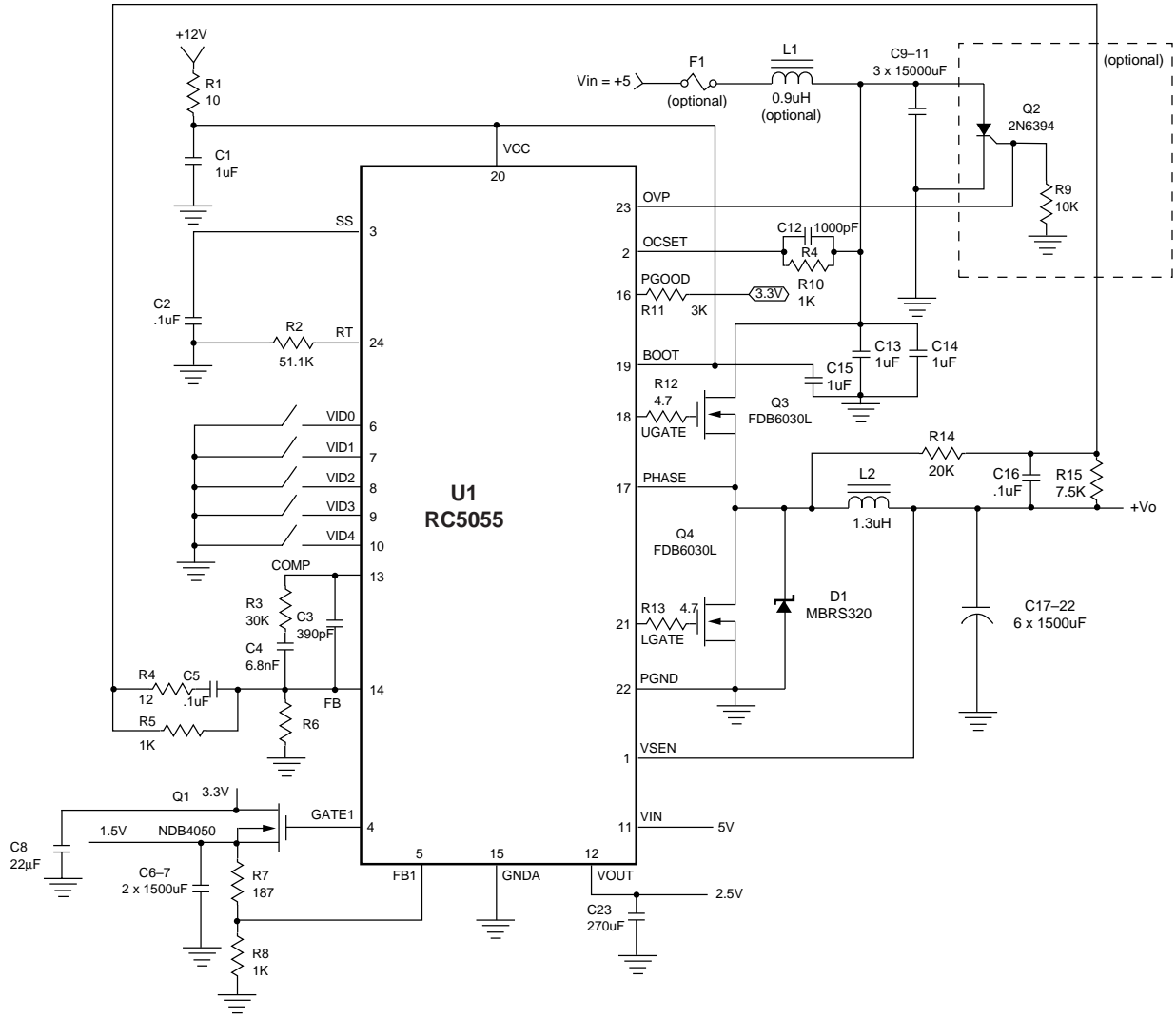


Figure 1. Deschutes 400MHz DC-DC Converter

Table 1. Deschutes 400MHz DC-DC Converter Bill of Materials

Item	Manufacturer Part #	Quantity	Description	Requirements/Comments
C1, C13–15	Any	4	1 μ F, 16V Capacitor	
C2, C5, C16	Any	3	100nF, 50V Capacitor	
C3	Any	1	390pF, 50V Capacitor	
C4	Any	1	6.8nF, 50V Capacitor	
C6–7, C17–22	Sanyo 6MV1500GX	8	1500 μ F, 6.3V Electrolytic	ESR \leq 44m Ω
C8		1	22 μ F, 16V Capacitor	
C9–11	Sanyo 10MV1200GX	3	1200 μ F, 10V Electrolytic	I _{RMS} = 2A
C12	Any	1	1nF, 50V Capacitor	
C23	Sanyo 6MV270GX	1	270 μ F, 6.3V Electrolytic	
D1	Fairchild MBRS320L	1	3A, 20V Schottky Diode	
L1	Any	Optional	0.9 μ H inductor	See Note 1.
L2	Any	1	1.3 μ H inductor1.3 μ H	See Note 2.
Q1	Fairchild NDB4050	1	N-Channel MOSFET	
Q2	Motoraola 2N6394	1	SCR	
Q3–4	Fairchild FDB6030L	2	N-Channel MOSFET	R _{DS(ON)} =20m Ω @ V _{GS} = 4.5V
R1	Any	1	10 Ω	
R2	Any	1	51.1K Ω	
R3	Any	1	30.1K Ω	
R4	Any	1	12 Ω	
R5, R8, R10	Any	3	1K Ω	
R6	Any	1		Used to adjust output voltage offset.
R7	Any	1	187 Ω	
R9	Any	1	10K Ω	
R11	Any	1	3.01K Ω	
R12–13	Any	2	4.7 Ω	
R14	Any	1	20K Ω	
R15	Any	1	7.5K Ω	
F1	Littelfuse	1	12A, 32V fast-acting fuse	
U1	Fairchild RC5055M	1	DC/DC Controller	

Notes:

- 12 turns of 16AWG wire on mocrmetals T60-2 core.
- 9 turns of 16AWG wire on Micrometals T50-8/90 core.

Applications

Increasing the Clock Current

The RC5055 can produce as much as 100mA of current at 2.5V for powering the motherboard's clock chips. If additional current capability is required, an external PNP transistor may be used to enhance the current to 600mA or more, as

shown in Figure 2. This circuit also provides a measure of current limit by letting the first 100mA of current be sourced through the 6.8Ω resistor, so that if too much collector, and thus base, current is demanded, the RC5055 cuts off the drive to the base.

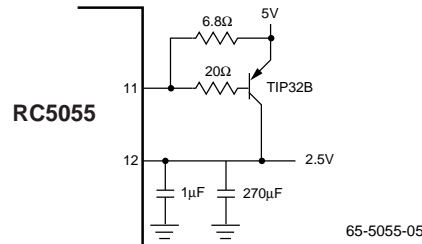


Figure 2. Boosting the Clock Current

Table 2. Output Voltage Table

PIN NAME					NOMINAL OUTPUT VOLTAGE	PIN NAME					NOMINAL OUTPUT VOLTAGE
VID4	VID3	VID2	VID1	VID0		VID4	VID3	VID2	VID1	VID0	
0	1	1	1	1	1.30	1	1	1	1	1	2.0
0	1	1	1	0	1.35	1	1	1	1	0	2.1
0	1	1	0	1	1.40	1	1	1	0	1	2.2
0	1	1	0	0	1.45	1	1	1	0	0	2.3
0	1	0	1	1	1.50	1	1	0	1	1	2.4
0	1	0	1	0	1.55	1	1	0	1	0	2.5
0	1	0	0	1	1.60	1	1	0	0	1	2.6
0	1	0	0	0	1.65	1	1	0	0	0	2.7
0	0	1	1	1	1.70	1	0	1	1	1	2.8
0	0	1	1	0	1.75	1	0	1	1	0	2.9
0	0	1	0	1	1.80	1	0	1	0	1	3.0
0	0	1	0	0	1.85	1	0	1	0	0	3.1
0	0	0	1	1	1.90	1	0	0	1	1	3.2
0	0	0	1	0	1.95	1	0	0	1	0	3.3
0	0	0	0	1	2.00	1	0	0	0	1	3.4
0	0	0	0	0	2.05	1	0	0	0	0	3.5

Note:

1. 0 = connected to GND or VSS, 1 = OPEN

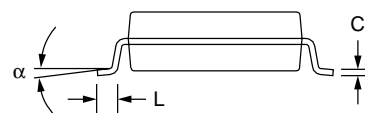
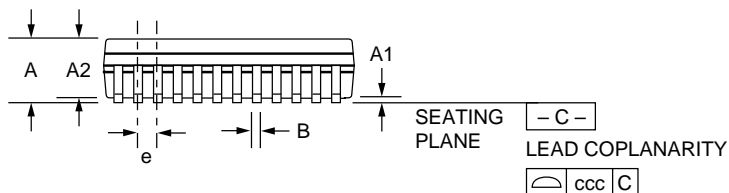
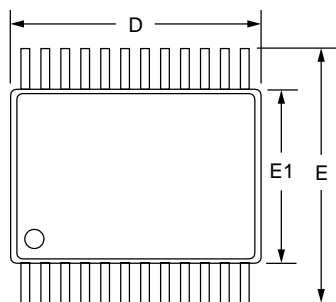
Package Dimensions

24-pin SSOP package

Symbol	Inches		Millimeters		Notes
	Min.	Max.	Min.	Max.	
A	—	.078	—	2.00	
A1	.002	—	0.05	—	
A2	.065	.073	1.65	1.85	
b	.010	.015	0.22	0.38	5
c	.0035	.010	0.09	0.25	5
D	.311	.335	7.90	8.50	2, 4
E	.291	.323	7.40	8.20	
E1	.197	.220	5.00	5.60	2
e	.026 BSC		0.65 BSC		
L	.022	.037	0.55	0.95	3
N	24		24		6
α	0°	8°	0°	8°	
ccc	—	.004	—	0.10	

Notes:

1. Dimensioning and tolerancing per ANSI Y14.5M-1982.
2. "D" and "E" do not include mold flash. Mold flash or protrusions shall not exceed .006 inch (0.15mm).
3. "L" is the length of terminal for soldering to a substrate.
4. Terminal numbers are shown for reference only.
5. "b" and "c" dimensions include solder finish thickness.
6. Symbol "N" is the maximum number of terminals.

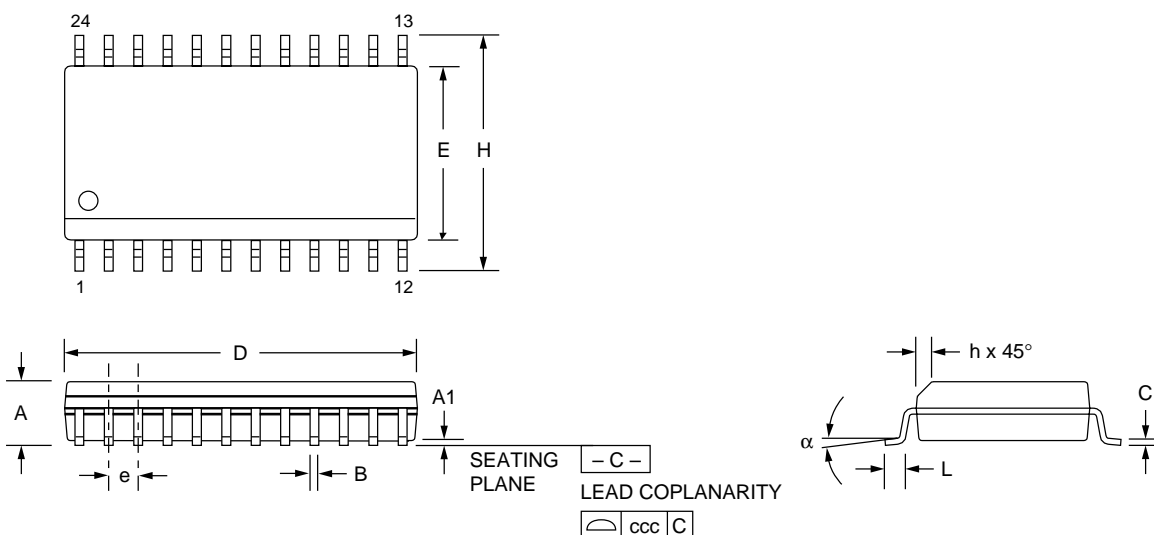


24-pin .300 mil SOIC package

Symbol	Inches		Millimeters		Notes
	Min.	Max.	Min.	Max.	
A	.093	.104	2.35	2.65	
A1	.004	.012	0.10	0.30	
B	.013	.020	0.33	0.51	
C	.009	.013	0.23	0.32	5
D	.599	.614	15.20	15.60	2
E	.290	.299	7.36	7.60	2
e	.050 BSC		1.27 BSC		
H	.394	.419	10.00	10.65	
h	.010	.020	0.25	0.51	
L	.016	.050	0.40	1.27	3
N	24		24		6
α	0°	8°	0°	8°	
ccc	—	.004	—	0.10	

Notes:

1. Dimensioning and tolerancing per ANSI Y14.5M-1982.
2. "D" and "E" do not include mold flash. Mold flash or protrusions shall not exceed .010 inch (0.25mm).
3. "L" is the length of terminal for soldering to a substrate.
4. Terminal numbers are shown for reference only.
5. "C" dimension does not include solder finish thickness.
6. Symbol "N" is the maximum number of terminals.



Notes

Ordering Information

Product Number	Package
RC5055G	24 pin SSOP
RC5055M	24 pin SOIC

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